

DS22W~DS220W

Rev.C Feb.-2015

描述 / Descriptions

表面贴装肖特基整流二极管，反向电压：20~200V，正向电流：2.0A，薄型 SOD-123FL 封装。
Surface Mount Schottky Barrier Rectifier, Reverse Voltage: 20 to 200 V, Forward Current: 2.0A, SOD-123FL thin package。

特征 / Features

低功耗，高效率，浪涌电流大，应用于低压、高频转换和极性保护，适用于表面贴装。无卤产品。
Low power loss, high efficiency, High forward surge current capability, For use in low voltage, high frequency inverters, and polarity protection applications, For surface mounted applications. Halogen free product.

用途 / Applications

一般用途。
General purpose.

内部等效电路 / Equivalent Circuit

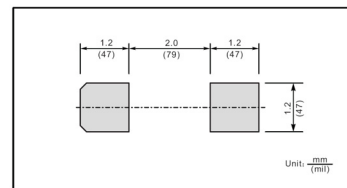


引脚排列 / Pinning



PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



印章代码 / Marking

见印章说明。See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating								单位 Unit
		DS22W	DS24W	DS26W	DS28W	DS210W	DS212W	DS215W	DS220W	
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	20	40	60	80	100	120	150	200	V
Maximum RMS Voltage	V _{RMS}	14	28	42	56	70	84	105	140	V
Maximum DC Blocking Voltage	V _{DC}	20	40	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current	I _{F(AV)}	2.0								A
Peak Forward Surge Current,8.3ms Single Half sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	50				40				A
Typical Junction Capacitance ¹⁾	C _i	220			80					pF
Operating Junction Temperature Range	T _j	-55~+125								°C
Storage Temperature Range	T _{stg}	-55~+150								°C

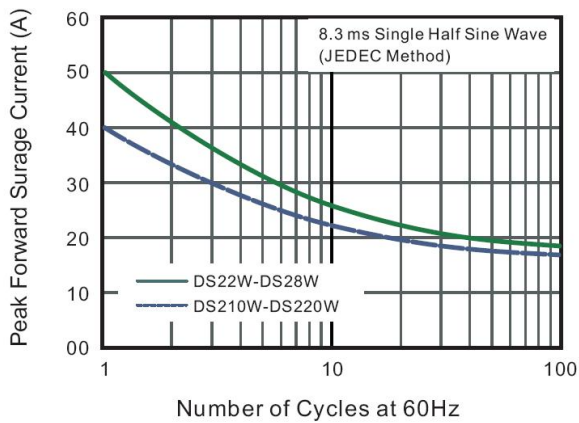
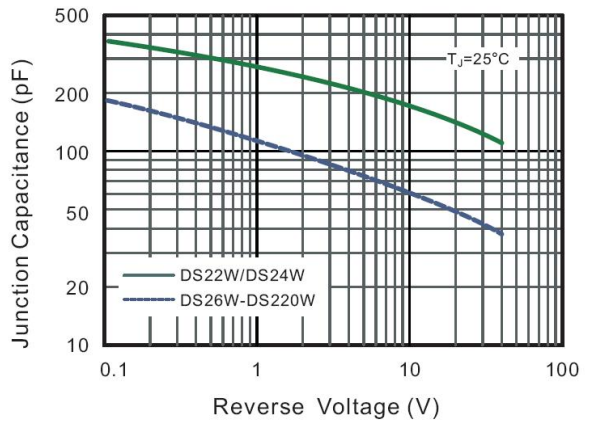
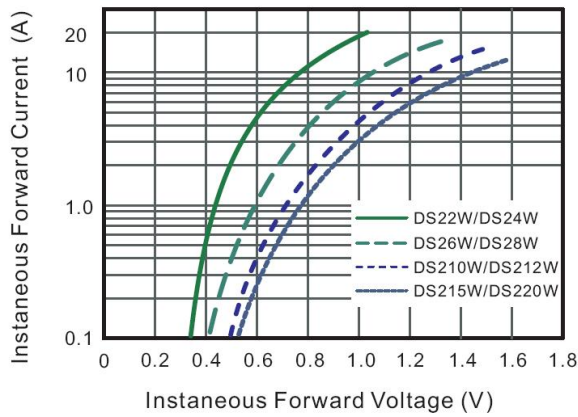
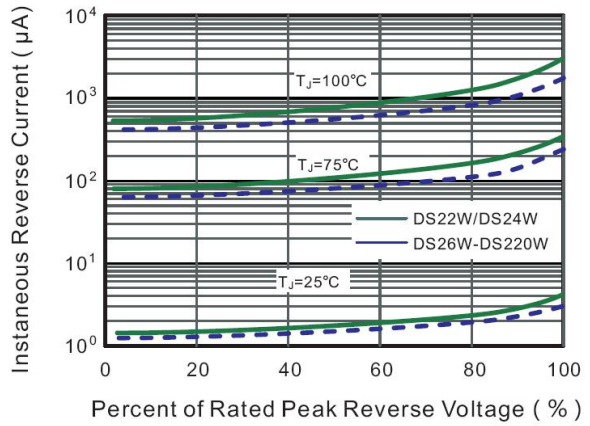
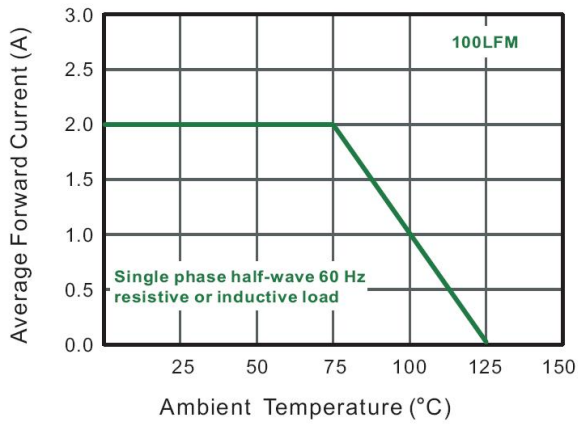
Note:

1) Measured at 1MHz and applied reverse voltage of 4 V D.C.

电性能参数 / Electrical Characteristics(Ta=25°C)

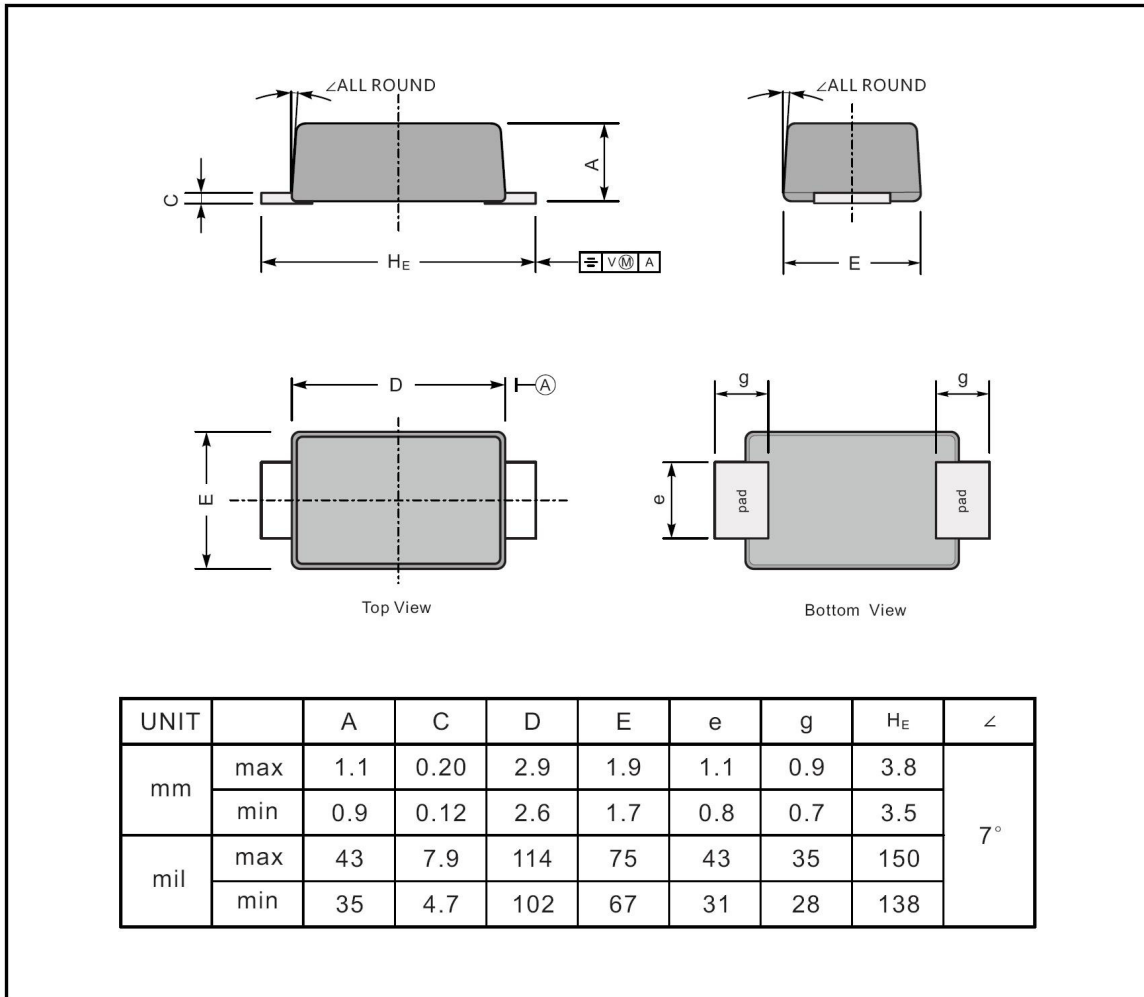
参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating							单位 Unit	
			DS22W	DS24W	DS26W	DS28W	DS210W	DS212W	DS215W		DS220W
Max Instantaneous Forward Voltage	V _F	I _F =2.0A	0.55		0.70		0.85		0.95		V
Maximum DC Reverse Current at Rated DC Reverse Voltage	I _R	T _a =25°C	0.5			0.3					mA
		T _a =100°C	5.0			5.0					

电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

SOD-123FL



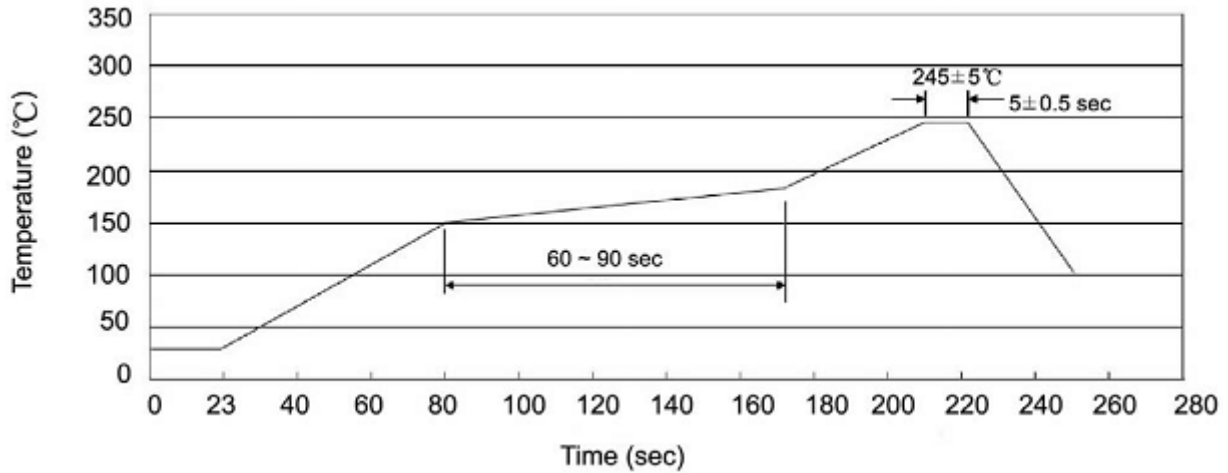


印章说明 / Marking Instructions

Marking

Type number	Marking code
DS22W	S22
DS24W	S24
DS26W	S26
DS28W	S28
DS210W	S210
DS212W	S212
DS215W	S215
DS220W	S220

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOD-123FL	3000	8	24000	5	120000	7" ×11	185X180X105	550X210X220

使用说明 / Notices